

## C1206C180K8HACTU

Aliases (C1206C180K8HAC7800) SMD Comm X8R HT150C, Ceramic, 18 pF, 10%, 10 VDC, X8R, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X8R HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	17 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1206	
L	3.2mm +/-0.2mm	
W	1.6mm +/-0.2mm	
т	0.78mm +/-0.10mm	
S	1.5mm MIN	
В	0.5mm +/-0.25mm	

# Packaging Specifications Packaging

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	18 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	10 VDC
Dielectric Withstanding Voltage	25 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MegaHz 1.0Vrms
Dissipation Factor	2.5%1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

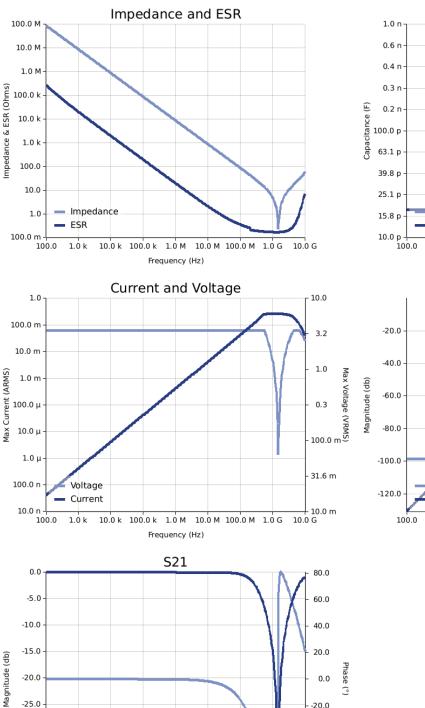
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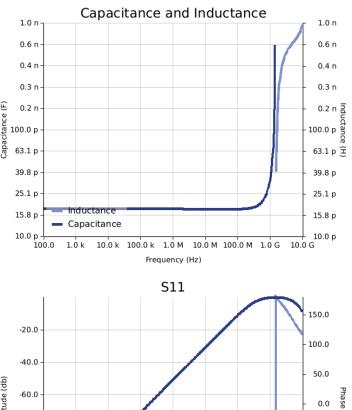


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### Simulations

For the complete simulation environment please visit K-SIM.





10.0 k 100.0 k 1.0 M 10.0 M 100.0 M 1.0 G

Frequency (Hz)

11 Phase

1.0 k

°)

-20.0

-40.0

-60.0

-80.0

S11 Magnitude

100.0

-25.0

-30.0

-35.0 -

-40.0

S21 Phase

S21 Magnitude

1.0 k 10.0 k 100.0 k 1.0 M 10.0 M 100.0 M 1.0 G 10.0 G

Frequency (Hz)

°

-50.0

-100.0

-150.0

10.0 G



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#### These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
  The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The effects shown herein are based on measured data from a multiple part sample of the parts in question.
  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages are applied to reach previous the burger of the parts.
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.